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THANK YOU PACK EXPO EXHIBITORS

for Your Generous Contributions to the 2006 PACK EXPO SCHOLARSHIP PROGRAM

PLATINUM

(\$5,000 and up):



GOLD

(\$1,000 to \$4,999):

A-B-C Packaging Machine Corp
B & H Labeling Systems
CVC Technologies, Inc.
Econocorp, Inc.
FOX IV Technologies, Inc.
Fres-co System USA Inc.
Greydon, Inc.
National Adhesives
Nordson Corporation
Omega Design Corporation
Omni Technologies, Inc.
Optima Machinery Corporation

PAC Machinery Group
Packaging Aids Corporation
Packaging Technologies
Paperboard Packaging Alliance
PIAB, Inc.
Pro Mach, Inc.
Raque Food Systems, LLC
Rovema Packaging Machines
Septimatech Group Inc.
Siemens Energy and Automation, Inc.
Zip-Pak

SILVER

(\$250 to \$999):

ABI Marketing Public Relations
Allen Field Companies Inc.
Algus Packaging Inc.
Bell-Mark Sales Company
Bimba Manufacturing Company
Combi Packaging Systems LLC
COVAL SAS
Douglas Machine Inc.
Edson Packaging Machinery Ltd.
Elsner Engineering Works, Inc.
ESS Technologies, Inc.
Garvey Corporation
Gemel Precision Tool Co., Inc.
George Gordon Associates, Inc.
Goodman Packaging Equipment
IASE, Co., Inc.
ICS Inex Inspection Systems, Inc.
J.W. Winco, Inc.
Label-Aire, Inc.
Marlen Research Corporation
MASSMAN Automation Design, LLC

Materials Handling Systems, Inc.
MAXCO Supply, Inc.
Moen Industries
NJM/CLI Packaging Systems Int'l.
Oden Corporation
Olcott Plastics
Packaging Digest
Packaging Machines International
Packaging World
Paper Machinery Corporation
Poly-Clip System Corp.
Scandia Packaging Machinery Co.
Schneider Packaging Equipment Co., Inc.
Sencorp, Inc.
Squid Ink Manufacturing, Inc.
Süd-Chemie Performance Packaging
Tipper Tie, Inc.
Triangle Package Machinery Co.
Weber Marking System, Inc.
Weiler Labeling Systems, Inc.

OTHER

Dynamic Conveyor Corp
Julie Static Controls Inc.

Package Design Magazine

PACK EXPO Scholarship Designated Gift Fund – Companies or individuals who donated \$5,000 or more to the PACK EXPO Scholarship effort were able to designate a specific school to which the funds they provided would be directed. \$20,000 was designated to specific schools from four sponsor companies. The following schools received designated gifts:

- **Virginia Polytechnic Institute** – BluePrint Automation Inc.
- **Univ. of Wisconsin, Stout** – Bosch Packaging Technology
- **University of Illinois at Urbana** – Morrison Container Handling Solutions
- **Michigan State University** – PPI Technologies

“Working together, PMMI and the PACK EXPO exhibitor community made a strong commitment to the future of the industry through financial aid,” said Chuck Yuska, president and CEO, PMMI. “Because of their support, hundreds of students will be able to further their education and become packaging professionals.”

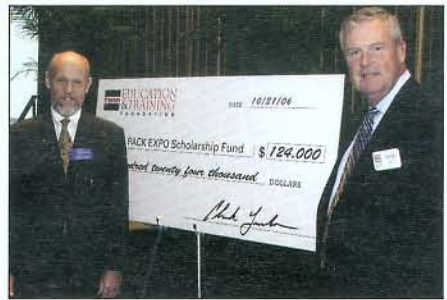
PMMI underwrote all of the marketing and development efforts to ensure that 100% of the funds raised would be donated directly to schools to benefit students.

PACK EXPO Scholarship recipients were announced and honored at the Future Packaging Leaders luncheon at PACK EXPO International in Chicago, Illinois on October 31, 2006.

Yuska opened the luncheon with a brief speech on the importance of funding education in the packaging industry and then a video presentation on Packaging as a career was shown.

Bruce Larson, vice president of sales at Goodman Packaging and PMMI’s Education and Workforce Development Committee Chairman, honored the contributing companies and distributed the funds. Many of the over 600 packaging students who attended PACK EXPO had the opportunity to meet and network with various industry leaders during the luncheon.

“Today’s students are the source of innovative new ideas and fresh solutions which will help drive the continued success of the packaging machinery industry,”



Chuck Yuska, president and CEO of PMMI and Bruce Larson, chairman of the education and workforce development committee and vice president of Goodman Packaging, pose next to the check which was donated by PACK EXPO exhibitors and PMMI and distributed during the Future Leaders Luncheon.

added Yuska. “With thousands of professionals, students, universities and technical schools supporting the show, PACK EXPO was the perfect opportunity to recognize the next generation of leaders.”

For more information about PMMI’s scholarship program, contact Maria Ferrante, director of workforce development at maria@pmmi.org or (703) 243-8555. ■

PLATINUM DONORS

- ★ BluePrint Automation Inc.
- ★ Bosch Packaging Technology
- ★ MG America, Inc.
- ★ Morrison Container Handling Solutions
- ★ PPI Technologies
- ★ PMT Magazine
- ★ WeighPack Systems, Inc.

GOLD DONORS

- ★ A-B-C Packaging Machine Corp.
- ★ B & H Labeling Systems
- ★ CVC Technologies, Inc.
- ★ Econocorp, Inc.
- ★ FOX IV Technologies, Inc.
- ★ Fres-Co System USA Inc.
- ★ Greydon, Inc.
- ★ National Adhesives
- ★ Nordson Corporation
- ★ Omega Design Corporation
- ★ Omni Technologies, Inc.
- ★ Optima Machinery Corporation
- ★ PAC Machinery Group
- ★ Packaging Aids Corporation
- ★ Packaging Technologies
- ★ Paperboard Packaging Alliance

- ★ PIAB, Inc.
- ★ Pro Mach, Inc.
- ★ Raque Food Systems, LLC
- ★ Rovema Packaging Machines
- ★ Septimatech Group Inc.
- ★ Siemens Energy and Automation, Inc.
- ★ Zip-Pak

SILVER DONORS

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- ★ Bimba Manufacturing Company
- ★ Combi Packaging Systems LLC
- ★ COVAL SAS
- ★ Douglas Machine Inc.
- ★ Edson Packaging Machinery Ltd.
- ★ Elsner Engineering Works, Inc.
- ★ ESS Technologies, Inc.
- ★ Garvey Corporation
- ★ Gemel Precision Tool Co., Inc.
- ★ George Gordon Associates, Inc.
- ★ Goodman Packaging Equipment
- ★ IASE, Co., Inc.
- ★ ICS Inex Inspection Systems, Inc.
- ★ J.W. Winco, Inc.
- ★ Label-Aire, Inc.

- ★ Marlen Research Corporation
- ★ MASSMAN Automation Design, LLC
- ★ Materials Handling Systems, Inc.
- ★ MAXCO Supply, Inc.
- ★ Moen Industries
- ★ NJM/CLI Packaging Systems Int'l.
- ★ Oden Corporation
- ★ Olcott Plastics
- ★ Packaging Digest
- ★ Packaging Machines International
- ★ Packaging World
- ★ Paper Machinery Corporation
- ★ Poly-Clip System Corp.
- ★ The Arthur G. Russell Co. Inc.
- ★ Scandia Packaging Machinery Co.
- ★ Sencorp, Inc.
- ★ Squid Ink Manufacturing, Inc.
- ★ Süd-Chemie Performance Packaging
- ★ Tipper Tie, Inc.
- ★ Triangle Package Machinery Co.
- ★ Weber Marking System, Inc.
- ★ Weiler Labeling Systems, Inc.

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PACK EXPO SCHOLARSHIP FUND EXCEEDS GOAL

The Packaging Machinery Manufacturers Institute (PMMI) and PACK EXPO exhibitors raised \$127,050 to support packaging education, eclipsing the announced \$100,000 goal. Designed to provide packaging schools across the U.S. and Canada with financial grants, PMMI created two PACK EXPO Scholarship Funds to which companies and individuals could donate funds:

PACK EXPO Scholarship General Fund – Contributions to this fund were distributed evenly among schools that have a packaging curriculum focus and exhibit at PACK EXPO. The schools will be asked to name a student recipient. This year, 19 packaging schools divided up \$107,050 in financial support, with \$35,000 being designated to 2-year technical schools through the Claude Breeden and C. Glenn Davis Scholarship programs. Three Platinum donors contributed to the General Scholarship Fund: MG America, Inc., *PMT Magazine* and WeighPack Systems, Inc.

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